

ABSTRACT

5 A sub-fab area installation apparatus capable of reducing a power consumption
used in manufacturing of semiconductors is disclosed. The sub-fab area installation
apparatus includes: a vacuum pump configured to evacuate a processing gas from a
processing chamber of the semiconductor manufacturing equipment; a cooling unit
configured to cool a first circulation liquid used in the processing chamber; a heating unit
10 configured to heat a second circulation liquid used in the processing chamber; an abatement
device configured to detoxify the processing gas discharged from the vacuum pump; and a
cooling-liquid line configured to pass a cooling liquid therethrough. The cooling liquid is
supplied from a cooling source. The cooling-liquid line includes: a first downstream line, a
second downstream line, and a third downstream line configured to supply the cooling liquid
15 that has passed through the abatement device, the vacuum pump, and the cooling unit to the
heating unit.

FIG. 2